

→ Our Sales network reinforced in Japan!

SET is very pleased to announce its new partnership with **Marubun Corporation**. Marubun, a 70 years company, has its headquarters based in Tokyo, and several branch offices all over Japan. This partnership will bring new values to the final end users thanks to the strong experience of our Marubun team in Japan.



Below is the contact information of the salesman in charge of SET's flip-chip bonders.

MARUBUN CORPORATION

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→ SET equipment: HVM machine installed at CEA-Leti

After several years in brainstorming, design and qualification in SET facilities, our project for a precise and rapid equipment dedicated to High Volume Manufacturing (HVM) enters now into a new phase. The beta tool has been installed in CEA-Leti cleanroom during summer. First results obtained are very encouraging and both CEA and SET's teams will pursue the qualification on real electrical dies to be direct bonded onto wafer.



*FC1 Beta tool installed at CEA-Leti
(Grenoble, France)*



*Chips direct bonded onto a Ø200 mm wafer
on FC1 Beta tool at SET*

As a reminder, this project is part of IRT Nanoelec 3D Integration Program. More information can be found here: <http://www.set-sas.fr/en/mpg2-793209--SET-is-proud-to-announce-a-new-and-important-partnership-.html>

→ Exhibitions and Conferences: when and where meeting SET until end 2017

Since summer this year, SET has already attended to **Semicon West** in San Francisco (USA), **Semicon Taiwan** in Taipei and **CIOE** in Shenzhen (China) with the kind and appreciated support of our local agents: SET-NA in USA, DKSH in Taiwan and SÜSS MicroTec in China.

SET was at **EMPC** in Warsaw (Poland) mid-September where Caroline Avrillier presented a paper named “Flip-chip bonding: how to meet the high accuracy requirement” (available on our Website).

SET will be at **IWLPC** in San Jose (USA) on October 24th/26th on booth #68 where Pascal Metzger will also present a paper named “Toward a Flip-Chip Bonder Dedicated to Direct Bonding for Production Environment”.

SET will also be at **Semicon Europa** in München (Germany) on November 14th/17th at the same time and place than **Productronica**. Our sales team and our agent for Switzerland and Germany will welcome every visitors on our booth #B1-1831.



SÜSS MicroOptics / SET booth at CIOE – China



SET booth at Semicon Taiwan